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TITLE: TEPBGA-I, 561 I/O, 23 X 23 PKG, 0.8 MM PITCH	DOCUMENT NO: 98ASA00181D	REV: 0	
	CASE NUMBER: 2113-01	29 JUN 2012	
	STANDARD: NON-JEDEC		

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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